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Doc. No. ESEC-P32US-D1

CP 3729/18

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Schindler, S.  
SERIAL NO.: 09/726,736  
FILING DATE: November 29, 2000  
TITLE: SEMICONDUCTOR MOUNTING APPARATUS WITH A CHIP GRIPPER TRAVELING BACK AND FORTH  
EXAMINER: Chang, R. K.  
ART UNIT: 3729

**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class  
Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on  
the date printed below:

Date: 8/2/02

Name: Diane Morse  
Diane Morse

COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

**TRANSMITTAL LETTER**

Enclosed for filing are the following documents:

1. Amendment.

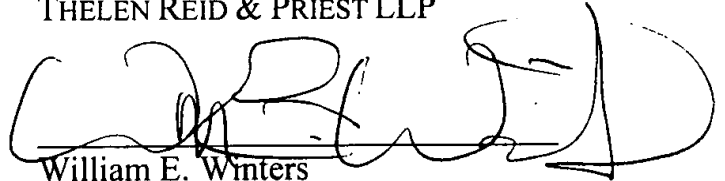
Enclosed is our check in the amount of \$156.00 as required for the filing fee,  
calculated as follows:

1 Additional Independent Claim @ \$84.00:	\$ 84.00
3 Additional Claims @ \$18.00:	\$ 72.00
Total Filing Fee:	\$ 156.00

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The Commissioner is hereby authorized to charge our Deposit Account No. 50-1698 for any fees for filing the above-noted document, including any fees required under 37 CFR § 1.136 for any necessary Extension of Time to make the filing of the attached document timely. A duplicate copy of this page is enclosed.

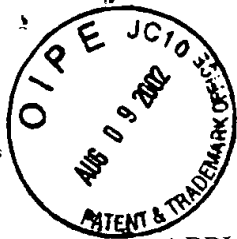
Respectfully submitted,  
THELEN REID & PRIEST LLP

A large, stylized handwritten signature in black ink, appearing to read 'Winters', is written over a horizontal line.

William E. Winters  
Reg. No. 42,232

Dated: August 2, 2002

THELEN REID & PRIEST LLP  
P.O. Box 640640  
San Jose, CA 95164-0640  
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Assistant Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT**

In response to the Office Action dated May 2, 2002, please amend the above-identified application as follows.

**IN THE CLAIMS:**

Please amend claims 15-36 as follows:

15. (Once Amended) An apparatus used as a component of a die bonder for placing a semiconductor chip on a substrate, comprising:

B1  
Sub 37  
E